

Title (en)

METHODS AND APPARATUS FOR PROCESSING A SUBSTRATE

Title (de)

VERFAHREN UND VORRICHTUNG ZUR VERARBEITUNG EINES SUBSTRATS

Title (fr)

PROCÉDÉ ET DISPOSITIF DE TRAITEMENT D'UN SUBSTRAT

Publication

EP 1976806 A4 20110810 (EN)

Application

EP 06844980 A 20061207

Priority

- US 2006046765 W 20061207
- US 29929505 A 20051209
- US 29855505 A 20051209

Abstract (en)

[origin: WO2007070353A2] Apparatus and methods adapted to polish an edge of a substrate include a polishing film, a frame adapted to tension and load the polishing film so that at least a portion of the film is supported in a plane, and a substrate rotation driver adapted to rotate a substrate against the plane of the polishing film such that the polishing film is adapted to apply force to the substrate, contour to an edge of the substrate, the edge including at least an outer edge and a first bevel, and polish the outer edge and the first bevel as the substrate is rotated. Numerous other aspects are provided.

IPC 8 full level

C03C 15/00 (2006.01)

CPC (source: EP KR)

B24B 9/065 (2013.01 - EP); **B24B 21/004** (2013.01 - EP); **H01L 21/02021** (2013.01 - EP); **H01L 21/304** (2013.01 - KR)

Citation (search report)

- [XYI] US 2004185751 A1 20040923 - NAKANISHI MASAYUKI [JP], et al
- [Y] US 6622334 B1 20030923 - ZIEMINS ULDIS A [US], et al
- See references of WO 2007070353A2

Designated contracting state (EPC)

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DOCDB simple family (publication)

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US 2006046765 W 20061207; EP 06844980 A 20061207; JP 2008544516 A 20061207; JP 2012100094 A 20120425; KR 20087015337 A 20061207; TW 95146154 A 20061208